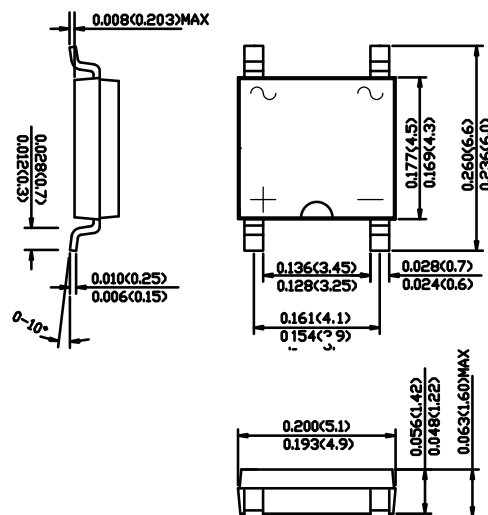


SINGLE PHASE GLASS PASSIVATED BRIDGE RECTIFIERS

Features

- ◆ Ideal for printed circuit board
- ◆ Reliable low cost construction utilizing molded plastic technique
- ◆ High temperature soldering guaranteed: 260°/10 seconds at 5 lbs., (2.3kg) tension
- ◆ Small size, simple installation
- ◆ High surge current capability
- ◆ Glass passivated chip junction



Mechanical Data

Case : JEDEC TBS Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.003 ounce, 0.098 grams

Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

| Parameter | SYMBOLS | MDD TB2S | MDD TB4S | MDD TB6S | MDD TB8S | MDD TB10S | UNITS | |
|---|-----------------|-------------|----------|----------|----------|-----------|-------|----------|
| Marking Code | | | | | | | | |
| Maximum repetitive peak reverse voltage | V_{RRM} | 200 | 400 | 600 | 800 | 1000 | V | |
| Maximum RMS voltage | V_{RMS} | 140 | 280 | 420 | 560 | 700 | V | |
| Maximum DC blocking voltage | V_{DC} | 200 | 400 | 600 | 800 | 1000 | V | |
| Maximum average forward rectified current | $I_{F(AV)}$ | 1.0 | | | | | | A |
| Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) | I_{FSM} | 30 | | | | | | A |
| Maximum instantaneous forward voltage drop per leg at 1A | V_F | 0.95 | | | | | | V |
| Maximum DC reverse current at rated DC blocking voltage | I_R | 5 100 | | | | | | uA |
| Typical thermal resistance | $R_{\theta JA}$ | 80 | | | | | | °C/W |
| Operating temperature range | T_J | -55 to +150 | | | | | | pF °C |
| storage temperature range | T_{STG} | -55 to +150 | | | | | | °C |

NOTES: 1. On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads
 2. On aluminum substrate P.C.B. with on area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad
 3. Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.

Ratings And Characteristic Curves

FIG.1 TYPICAL FORWARD CHARACTERISTICS

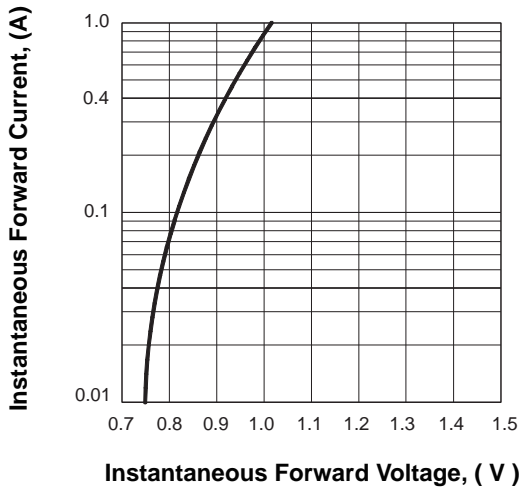


FIG.2 FORWARD DERATING CURVE

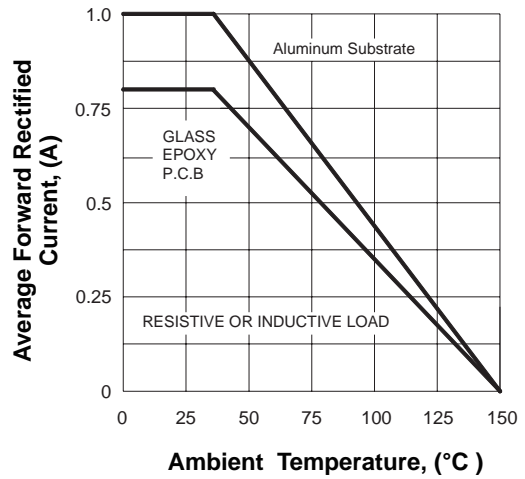


FIG.3 TYPICAL REVERSE CHARACTERISTICS

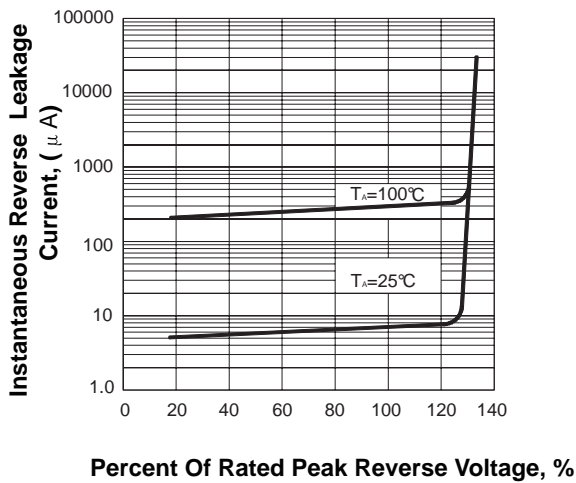
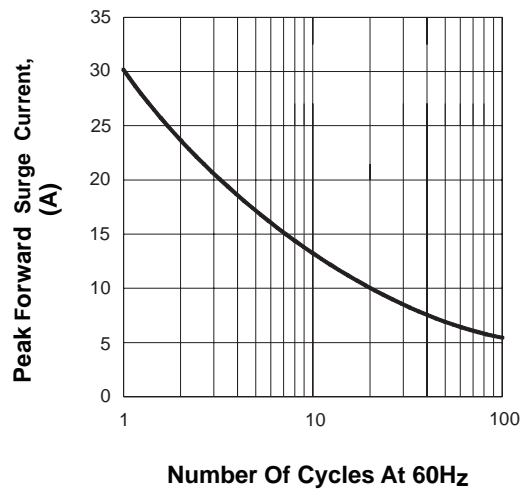


FIG.4 PEAK FORWARD SURGE CURRENT



The cruve graph is for reference only, can't be the basis for judgment